

TECHNICAL DATA SHEET



468-50, 468-1000 KLENZ Purging Compound

Product Description

KLENZ is a revolutionary purging compound requiring no mixing or preparation time. With operating temperatures of 330° - 610°F, KLENZ thoroughly cleanses hot runners and the barrel, helping to eliminate color streaking and black specs. Formulated with a polyolefin resin carrier, KLENZ purging compound is safe to purge right through the mold, saving time, material and money. All ingredients are GRAS rated so it is safe to use for food packaging applications. For use with injection molding, extrusion and blow molding.

Applications

Purging Compound

Unit Package Description

50 pound box

Generic Description

Purging Compound

Net Weight Fill

multiple sizes

UPC Code

858799000684

Units Per Case

multiple sizes

Case Weight (lbs)

53

Appearance

Resin Pellet

Flash Point F

>750 degrees

Flash Point C

>400 degrees

Base Type

Resin

Evaporation Rate

N/A

Working Temperature F

330 to 610 degrees

Working Temperature C

165 to 321 degrees

Propellant

N/A

NFPA Aerosol Flammability Level

N/A

DOT Proper Shipping Name

Not regulated, Granules, NOI

VOC % (Federal)

0

VOC g/L (Federal)

0

VOC lbs./Gal (Federal)

0

Removal

N/A